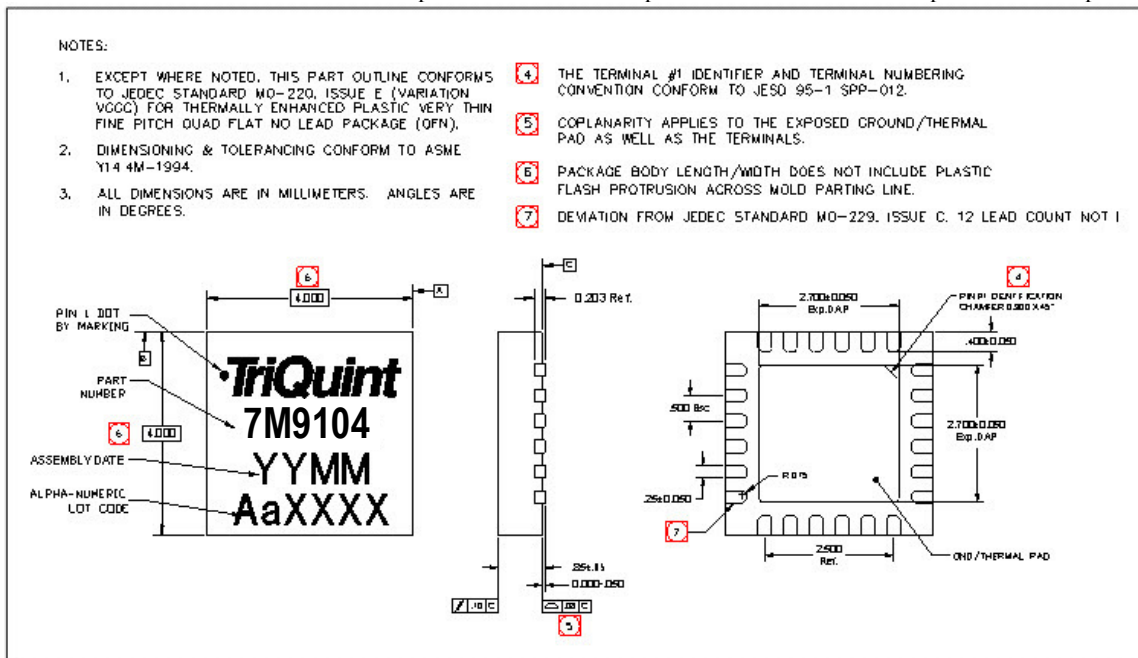


Mechanical Information

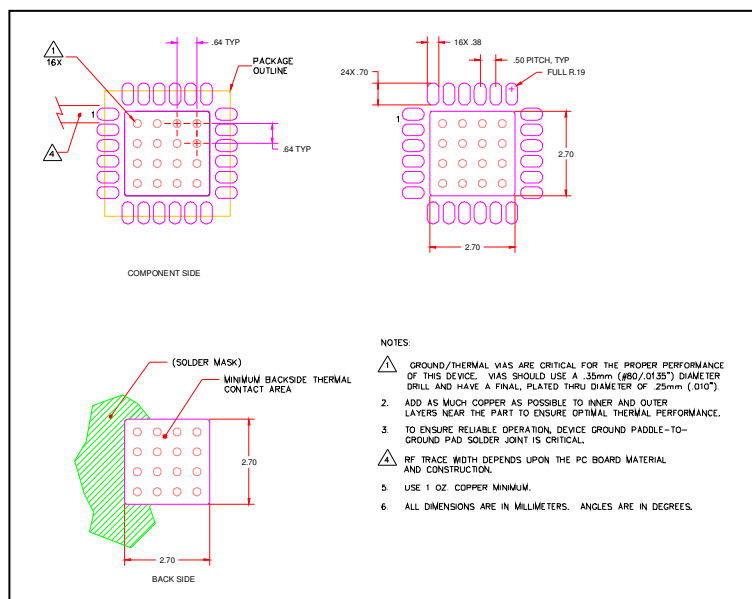
Package Information and Dimensions

This package is lead-free, RoHS-compliant, and green. The plating material on the pins is annealed matte tin over copper. It is compatible with both lead-free (maximum 260 °C reflow temperature) and leaded (maximum 245 °C reflow temperature) soldering processes.

The component will be laser marked with “7M9104” product label with an alphanumeric lot code on the top surface of the package.



Mounting Configuration



All dimensions are in millimeters (inches). Angles are in degrees.

Notes:

- Ground vias are critical for the proper RF performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25mm (.010").
- Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.